

ABSTRACT OF THE DISCLOSURE

An exposure apparatus according to this invention comprises: a projection optical system having a
5 predetermined image forming characteristic; a reticle stage, arranged on one side of the projection optical system, which holds a reticle having a transfer pattern and has a reference plate for positioning; and a wafer stage, arranged on the other side of the projection
10 optical system, which holds a wafer where the transfer pattern is transferred and has a reference mark. For transferring the transfer pattern to the wafer, a reticle protection pellicle and an optical device are arranged between the reticle and the projection optical
15 system. For performing positioning using the reference plate and the reference mark, a correction optical device is arranged between the reference plate and the projection optical system. The correction optical device has an equal thickness to the total thickness of
20 the optical device and pellicle.